



## Product Change Notification: DSN0-15WOKT491

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**Date:**

18-Sep-2025

**Product Category:**

32-Bit Microprocessors

**Notification Subject:**

CCB 7737 Initial Notice: Qualification of ATP7 as an additional assembly site for selected AT91RM9200-CJ-101 and AT91RM9200-CJ-002 catalog part numbers (CPN) available in 256L LFBGA (15x15x1.25mm) package.

**Affected CPNs:**

[DSNO-15WOKT491\\_Affected\\_CPN\\_09182025.pdf](#)

[DSNO-15WOKT491\\_Affected\\_CPN\\_09182025.csv](#)

**PCN Status:** Initial Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of ATP7 as an additional assembly site for selected AT91RM9200-CJ-101 and AT91RM9200-CJ-002 catalog part numbers (CPN) available in 256L LFBGA (15x15x1.25mm) package.

**Pre and Post Summary Changes:**

	Pre Change	Post Change	
Assembly Site	ATX Semiconductor (Shanghai) Co. Ltd (ASSH)	ATX Semiconductor (Shanghai) Co. Ltd (ASSH)	Amkor Technology Philippines (P3/P4), INC. (ATP7)
Wire Material	Au	Au	Au
Die Attach Material	2100AS (PFAS)	2100AS (PFAS)	2300 (PFAS-free)

<b>Molding Compound Material</b>	KE-G1250	KE-G1250	G770FE
<b>Substrate Core Material</b>	HL832NX	HL832NX	HL832NS
<b>Substrate Material</b>	AUS308	AUS308	AUS308

### Impacts to Datasheet:

Yes. Refer to Package Outline Drawing (POD) comparison.

Dimension in mm		ASSH			ATP7		
		Min	Nom	Max	Min	Nom	Max
Number of Terminals	N	256			256		
Pitch	e	0.80 BSC			0.80 BSC		
Overall Height	A	-	-	1.25	-	-	1.25
Standoff	A1	0.25	0.3	0.35	0.22	0.32	-
Mold Thickness	A3	0.50 BSC			0.48	0.53	0.58
Overall Length	D	14.95	15	15.05	15.00 BSC		
Overall Width	E	14.95	15	15.05	15.00 BSC		
Terminal Diameter	b	0.35	0.40	0.45	0.36	0.41	0.46

**Change Impact:** None

**Reason for Change:** To improve on-time delivery performance by qualifying ATP7 as an additional assembly site.

**Change Implementation Status:** In Progress

**Estimated Qualification Completion Date:** April 2026

**Note:** Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

### Timetable Summary:

	September 2025					>	April 2026				
Work Week	36	37	38	39	40		14	15	16	17	18
Initial PCN Issue Date			X								
Qual Report Availability									X		
Final PCN Issue Date									X		

**Method to Identify Change:** Traceability Code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** September 18, 2025: Issued initial notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

### Attachments:

**PFAS Elimination and Die Attach\_Explanation.pdf**  
**PCN\_DSNO-15WOKT491\_Qual\_Plan.pdf**

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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